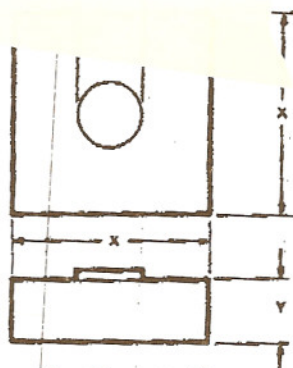




Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



**Outline 01B
Chip Dimensions**

DIMENSIONS	FOR EPOXY OR EUTECTIC DIE ATTA PART NO. HPND-		
	-0001	-0002	-0003
D (0.03) (1)	0.25 (10)	0.20 (8)	0.10 (4)
X (0.05) (2)	0.51 (20)	0.38 (15)	0.30 (12)
Y (0.03) (1)	0.15 (6)	0.15 (6)	0.13 (5)
TOP CONTACT	CATHODE	CATHODE	ANODE
BACK CONTACT			CATHODE

DII

Topside Metal: Al
Backside: Si
Backside Potential:
Mask Ref:
Bond Pads : .004 min

APPROVED BY: CB
MFG: Harris

DIE SIZE: .020" x .020"
THICKNESS: .020"

DATE: 2/6/01
P/N: HPND-3802

DG 10.1.2
 Rev A 3-4-99